

Taiwan Semiconductor

Switching Diode

FEATURES

- Fast switching speed
- Surface device type mounting
- Moisture sensitivity level 1
- High conductance power dissipation
- For general purpose switching applications
- Pb free version and RoHS compliant
- Packing code with suffix "G" means green compound (halogen-free)

MECHANICAL DATA

- Case: SOT-363 small outline plastic package
- Terminal: Matte tin plated, lead free., solderable per MIL-STD-202, Method 208 guaranteed
- High temperature soldering guaranteed : 260°C/10s





SOT-363



MAXIMUM RATINGS AND ELECTRICAL CHARACTERISTICS (T _A =25°C unless otherwise noted)				
PARAMETER		SYMBOL	VALUE	UNIT
Power Dissipation		PD	200	mW
Repetitive Peak Reverse Voltage		V _{RRM}	80	V
Reverse Voltage		V _R	57	V
Average Rectified Forward Current		I _{F(AV)}	500	mA
Average Rectified Output Current		Ι _Ο	250	mA
Non-Repetitive Peak Forward Surge Current	@ t = 1 µs	lan.	4	А
Non-Repetitive Feak Forward Surge Current	@ t = 1 s	I _{FSM}	1.5	
Thermal Resistance (Junction to Ambient)		R _{θJA}	625	°C/W
Junction and Storage Temperature Range		T _J , T _{STG}	-55 to 150	°C

PARAMETER		SYMBOL	MIN	MAX	UNIT
Reverse Breakdown Voltage	I _R =100μA	V _(BR)	80	-	V
	I _F =5.0mA		0.620	0.715	
	I _F =10mA	V	-	0.855	
Forward Voltage	I _F =100mA	V _F	-	1.000	— V
	I _F =150mA		-	1.250	
	V _R =70V		-	100	nA
Deverse Leekerse Current	V _R =75V, T _J =150°C	V	-	50	μA
Reverse Leakage Current	V _R =25V, T _J =150°C	V _F	-	30	μA
	V _R =20V		-	25	nA
Junction Capacitance	V _R =6V, f=1MHz	CJ	-	3.5	pF
Reverse Recovery Time	I _F =5mA, V _R =6V	t _{rr}	-	4.0	ns

Note 1: Device mounted on FR-4 PCB, 1 inch × 0.85 inch × 0.062 inch

Note 2: Short duration test pulse uesd tu minimize self-heating effect



MBD4448HAQW/HADW/HCDW/HSDW/HTW

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OPDEDING INFORMATION

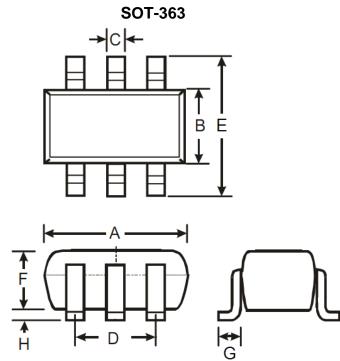
ORDERING INFORMATION				
PART NO.	PACKING CODE	PACKING CODE SUFFIX	PACKAGE	PACKING
MBD4448Hxxx (Note 1, 2)	RE	G	SOT-363	3K / 7" Reel

Note 1: "xxx" is Device Code from "AQW" - "TW"

Note 2: Whole series with green compound

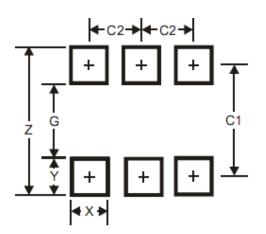
EXAMPLE				
PREFERRED P/N	PART NO.	PACKING CODE	PACKING CODE SUFFIX	DESCRIPTION
MBD4448HTW REG	MBD4448HTW	RE	G	Green compound

DIMENSIONS



DIM.	Unit (mm)		Unit (inch)	
Dilvi.	Min	Мах	Min	Мах
А	2.00	2.20	0.079	0.087
В	1.15	1.35	0.045	0.053
С	0.15	0.35	0.006	0.014
D	1.20	1.40	0.047	0.055
E	2.15	2.45	0.085	0.096
F	0.85	1.05	0.033	0.041
G	0.25	0.46	0.010	0.018
Н	0.00	0.10	0.000	0.004

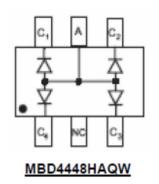
SUGGESTED PAD LAYOUT

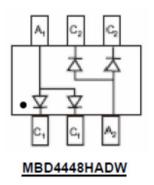


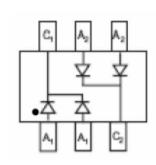
DIM.	Unit (mm)	Unit (inch)
Dilvi.	Тур.	Тур.
Z	2.50	0.098
G	1.30	0.051
Х	0.42	0.017
Y	0.60	0.024
C1	1.90	0.075
C2	0.65	0.026



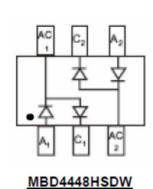
PIN CONFIGURATION

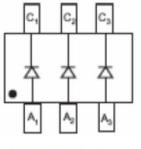






MBD4448HCDW





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MBD4448HTW

MARKING

Part no.	Marking code
MBD4448HAQW	KA5
MBD4448HADW	KA6
MBD4448HCDW	KA7
MBD4448HSDW	KA8
MBD4448HTW	KAA

Document Number: DS_S1501009



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